



DMNH6065SPDWQ

60V 175°C N-CHANNEL ENHANCEMENT MODE MOSFET POWERDI5060-8

Product Summary

BV _{DSS}	R _{DS(ON)} Max	I _D Max T _C = +25°C	
60V	65mΩ @ V _{GS} = 10V	27A	
	79mΩ @ V _{GS} = 4.5V	24A	

Description and Applications

This MOSFET is designed to meet the stringent requirements of automotive applications. It is qualified to AEC-Q101, supported by a PPAP, and is ideal for use in:

- Backlighting
- **Power Management Functions**
- **DC-DC Converters**

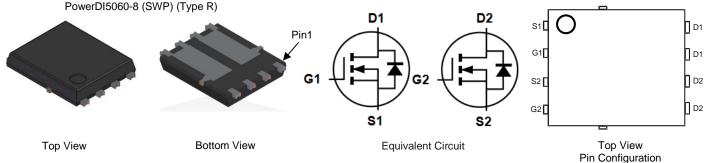
PowerDI5060-8 (SWP) (Type R)

Features and Benefits

- Rated to +175°C—Ideal for High-Ambient Temperature Environments
- 100% Unclamped Inductive Switch (UIS) Test in Production
- Low-Input Capacitance
- Wettable Flank for Improved Optical Inspections
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- PPAP Capable (Note 4)

Mechanical Data

- Case: PowerDI[®]5060-8
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish—Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 @3
- Weight: 0.097 grams (Approximate)



Ordering Information (Note 5)

Part Number	Case	Packaging
DMNH6065SPDWQ-13	PowerDI5060-8 (SWP) (Type R)	2500/Tape & Reel

1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.

2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. Automotive products are AEC-Q101 qualified and are PPAP capable. Refer to https://www.diodes.com/quality/.

5. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information

Notes:

ſ	D1 D1 D2 D2	
	211	Characteria Stress
	NH6065SPDW	YYWW = Date Code Marking YY = Year (ex: $19 = 2019$)
D	YY WW	WW = Week (01 to 53)
	S1 G1 S2 G2	



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Drain-Source Voltage	V _{DSS}	60	V	
Gate-Source Voltage	V _{GSS}	±20	V	
Continuous Drain Current, V _{GS} = 10V (Note 7)	T _C = +25°C T _C = +100°C	I _D	27 19	А
Maximum Body Diode Forward Current (Note 6)	I _S	2	А	
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)	IDM	108	А	
Pulsed Source Current (10µs Pulse, Duty Cycle = 1%)	I _{SM}	108	A	
Avalanche Current, L = 1mH		I _{AS}	13	А
Avalanche Energy, L = 1mH		E _{AS}	89	mJ

Thermal Characteristics

Characteristic	Symbol	Value	Unit	
Thermal Resistance, Junction to Ambient (Note 6)		R _{ÐJA}	62	°C/W
Total Power Dissipation	T _A = +25°C	PD	2.4	W
Thermal Resistance, Junction to Case (Note 7)	•	R _{θJC}	2.2	°C/W
Total Power Dissipation	$T_{\rm C} = +25^{\circ}{\rm C}$	PD	68	W
Operating and Storage Temperature Range	·	TJ, TSTG	-55 to +175	°C

Electrical Characteristics (@T_C = +25°C, unless otherwise specified.)

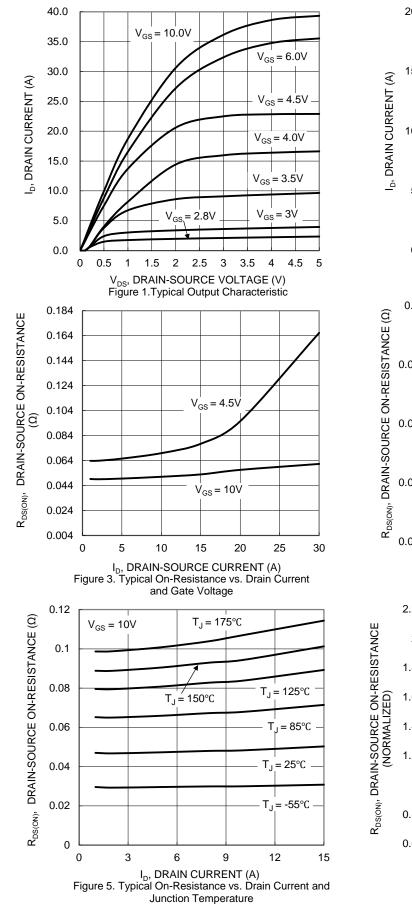
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 8)					1	
Drain-Source Breakdown Voltage	BV _{DSS}	60	—	_	V	$V_{GS} = 0V, I_D = 250\mu A$
Zero Gate Voltage Drain Current	I _{DSS}	_	—	1	μA	$V_{DS} = 60V, V_{GS} = 0V$
Gate-Source Leakage	IGSS	_	—	□100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 8)			•		•	·
Gate Threshold Voltage	V _{GS(TH)}	1	_	3	V	$V_{DS} = V_{GS}$, $I_D = 250 \mu A$
Static Drain-Source On-Resistance		_	53	65	mΩ	$V_{GS} = 10V, I_D = 15A$
Static Drain-Source On-Resistance	R _{DS(ON)}	_	68	79	11152	$V_{GS} = 4.5V, I_D = 7.5A$
Diode Forward Voltage	V _{SD}	_	—	1.3	V	$V_{GS} = 0V, I_S = 2.6A$
DYNAMIC CHARACTERISTICS (Note 9)						·
Input Capacitance	C _{iss}	_	466	—		$V_{DS} = 25V, V_{GS} = 0V,$ f = 1.0MHz
Output Capacitance	Coss	_	124	—	pF	
Reverse Transfer Capacitance	C _{rss}	_	9.9	—		
Gate Resistance	R _G	_	3.3	_	Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1.0MHz$
Total Gate Charge ($V_{GS} = 4.5V$)	Qg	_	4.6	—		
Total Gate Charge (V _{GS} = 10V)	Qg	_	9.5	—	nC	$V_{DS} = 30V, I_{D} = 20A$
Gate-Source Charge	Q _{gs}	_	1.3	—		$v_{DS} = 30v, I_D = 20A$
Gate-Drain Charge	Q _{gd}	_	2.9	—		
Turn-On Delay Time	t _{D(ON)}	_	3.3	—		
Turn-On Rise Time	t _R	_	4.6	—	-	$V_{DD} = 30V, V_{GS} = 10V,$
Turn-Off Delay Time	t _{D(OFF)}		12.6	—	ns	$R_{G} = 4.7\Omega, I_{D} = 20A$
Turn-Off Fall Time	tF		4.3	—		
Body Diode Reverse Recovery Time	t _{RR}	_	24	—	ns	I _F = 20A, di/dt = 100A/µs
Body Diode Reverse Recovery Charge	Q _{RR}	_	20	—	nC	I _F = 20A, di/dt = 100A/µs

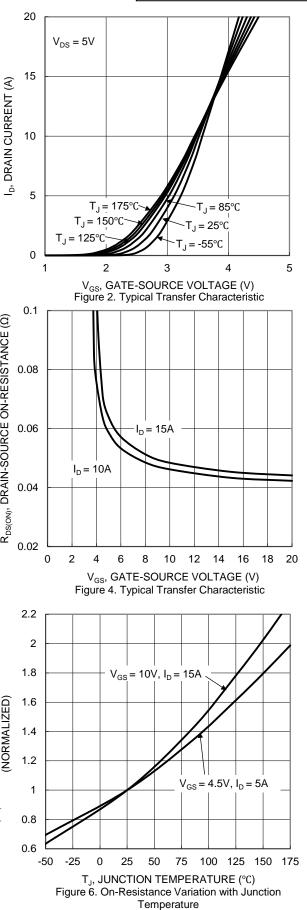
Notes:

6. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate. 7. Thermal resistance from junction to solder point (on the exposed drain pin).

8. Short duration pulse test used to minimize self-heating effect.
9. Guaranteed by design. Not subject to product testing.



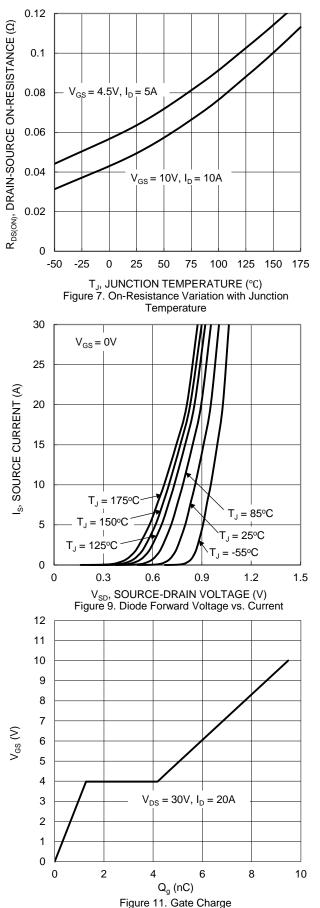


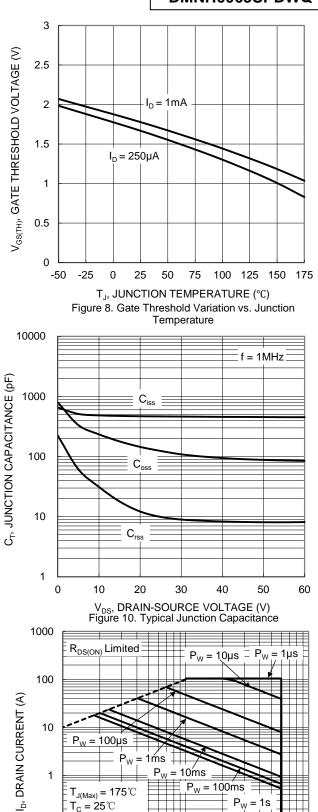


DMNH6065SPDWQ



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Single Pulse

heatsink

 $V_{GS} = 10V$

DUT on infinite

H

10

V_{DS}, DRAIN-SOURCE VOLTAGE (V)

Figure 12. SOA, Safe Operation Area

0.1

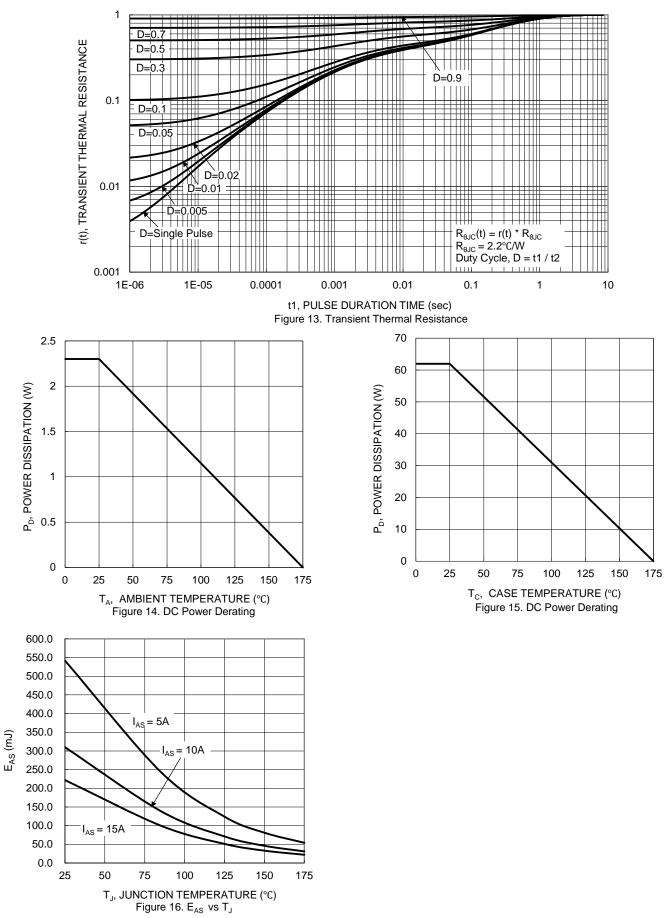
0.01

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100



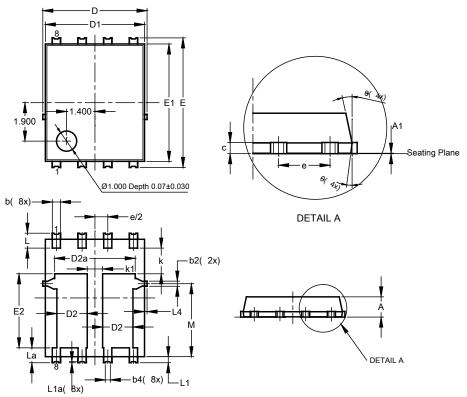
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Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.



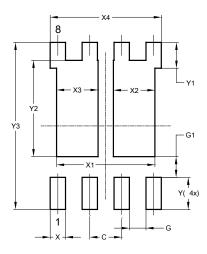
PowerDI5060-8 (SWP) (Type R) Dim Min Max Тур 0.90 1.10 1.00 Α A1 0 0.05 b 0.30 0.50 0.41 b2 0.20 0.35 0.25 b4 0.25REF 0.230 0.330 0.277 С D 5.15 BSC D1 4.70 5.10 4.90 D2 1.40 1.60 1.50 D2a 3.78 4.18 3.98 6.40 BSC Ε E1 5.60 6.00 5.80 E2 3.66 3.46 3.86 1.27BSC е k 1.05 -----0.56 k1 ------L 0.635 0.835 0.735 La 0.635 0.835 0.735 L1 0.200 0.400 0.300 L1a 0.050REF L4 0.025 0.225 0.125 Μ 3.205 4.005 3.605 θ 12° 10° 11° θ1 6° 8° 7°

All Dimensions in mm

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

PowerDI5060-8 (SWP) (Type R)



Dimensions	Value (in mm)
С	1.270
G	0.660
G1	0.820
Х	0.610
X1	3.910
X2	1.650
X3	1.650
X4	4.420
Y	1.270
Y1	1.020
Y2	3.810
Y3	6.610

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